

Application Data Sheet

Application Information

Application Type::	Regular
Subject Matter::	Utility
Suggested classification::	
Suggested Group Art Unit::	
CD-ROM or CD-R?::	None
Title::	Bump formation method and wire bonding method
Attorney Docket Number::	85A 3503
Request for Early Publication?::	No
Request for Non-Publication?::	No
Suggested Drawing Figure::	1
Total Drawing Sheets::	6
Small Entity::	Yes
Petition included?::	No
Secrecy Order in Parent Appl.?::	No

Applicant Information

Applicant Authority Type::	Inventor
Status::	Full Capacity
Given Name::	Tatsunari
Family Name::	Mii
Street::	6-18-11, Ichiban-cho
City::	Tachikawa-shi
State or Province::	Tokyo
Country::	Japan
Postal or Zip Code::	
Citizenship Country::	Japan

Correspondence Information

Correspondence Customer Number:: 003713
Phone number:: 310-277-1391
Fax Number:: 310-277-4118
E-Mail address:: patlawyr@ix.netcom.com

Representative Information

Representative Customer Number::	003713	
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Foreign Priority Information

Country::	Application number::	Filing Date::	Priority Claimed::
Japan	2003-038312	2/17/2003	Yes

Assignee Information

Assignee name:: Kabushiki Kaisha Shinkawa